ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES	position De IPC, Bannockt Pan-American co	claration ourn, Illinois. <i>A</i> opyright conve	All rights reserved u ntions.	nder both	This docume level parts, th	ent is a declaration er	on of the substan	ces within the man ower level material	ufacturer liste s for which th	ed item. Note: if e manufacturer	the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form T				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information			
upplier Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2024-04-30			
Contact Name Title - Conta			ntact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title -			itle - Representative			Phone - Representative*			Emai	Email - Representative*			
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number	Mfr Item Name		· · ·	Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FCH041	CH041N60E SF2 600V 41r		Ohm E TO247		2024-04-30		CP8		5456.725	mg	Each	
Ianufacturing Proccess Inform	ation					•							
Terminal Plating / Grid Array	y Material Terminal Base		Alloy J	J-STD-020 MSL Ratir		Peak Proce	Peak Process Body Temperature		at Peak Tempe	erature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0	0 C 30		see	conds 3				
omments													
or more information regarding materi	al composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measur
Die	32.0	mg	Supplier	Silicon (Si)	7440-21-3		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			А	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
Lead Frame	3612.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.75	mg
			В	Nickel (Ni)	7440-02-0		117.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.1	mg
			Supplier	Copper (Cu)	7440-50-8		3489.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Mold Compound-Black	1739.8	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		86.99	mg
			Supplier	Proprietary	Proprietary Data		86.99	mg
			Supplier	Carbon Black (C)	1333-86-4		8.699	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		78.291	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1304.8501	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		86.99	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		86.99	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg